

COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
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△					△				
APPLICABLE STANDARD									
RATING	OPERATING TEMPERATURE RANGE	-35 °C TO +85 °C(NOTE1)			STORAGE TEMPERATURE RANGE	-10 °C TO +60 °C(NOTE3)			
	OPERATING MOISTURE RANGE	20 %TO 80 %(NOTE2)			STORAGE MOISTURE RANGE	40 %TO 70 %(NOTE3)			
	CURRENT	1 A			VOLTAGE	150 V AC(DC)			
	SPECIFICATIONS								
ITEM		TEST METHOD			REQUIREMENTS			QT	AT
CONSTRUCTION									
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			ACCORDING TO DRAWING.			×	×
MARKING		CONFIRMED VISUALLY.						×	×
ELECTRIC CHARACTERISTICS									
CONTACT RESISTANCE		100 mA (DC OR 1000 Hz).			30 mΩ MAX.			×	—
CONTACT RESISTANCE- MILLIVOLT LEVEL METHOD.		20 mV MAX, 1mA(DC OR 1000 Hz)							
INSULATION RESISTANCE		100 V DC.			500 MΩ MIN.			×	—
VOLTAGE PROOF		500 V AC FOR 1 min.			NO FLASHOVER OR BREAKDOWN.			×	—
MECHANICAL CHARACTERISTICS									
MECHANICAL OPERATION		50 TIMES INSERTIONS AND EXTRACTIONS.			① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			×	—
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			① NO ELECTRICAL DISCONTINUITY OF 1 μs.			×	—
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			×	—
ENVIRONMENTAL CHARACTERISTICS									
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 →5 TO 35→+85 →5 TO 35°C TIME 30 →10 TO 15 →30 →10 TO15min UNDER 5 CYCLES.			① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN.			×	—
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 ~ 95 %, 96 h.			③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				
RESISTANCE TO SOLDERING HEAT		(1) REFLOW SOLDERING «REFLOW AREA» MAX 250°C WITHIN 10 sec. MIN 220°C WITHIN 70 sec «PREHEATING AREA» 150°C to 160 °C 60 sec. To 120 sec. PUT THROUGH IN REFLOW FUMACE TWICE. LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE 350±5°C, FOR 5±1 sec. NO STRENGTH ON CONTACT.			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			×	—
SOLDERABILITY		SOLDERING TEMPERATURE : 235±5°C DURATION OF IMMERSION : SOLDERING, FOR 3 sec.			A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.			×	—
REMARKS NOTE1:INCLUDING THE TEMPERATURE RISE BY CURRENT. NOTE2:NON-CONDENSING NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD, AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION. Unless otherwise specified, refer to JIS C 5402					DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
					<i>I. Denfouga</i> 03.03.05	<i>I. Denfouga</i> 03.03.05	<i>T. Miyajishi</i> 03.03.05	<i>T. Miyajishi</i> 03.03.05	
Note QT:Qualification Test AT:Assurance Test ×:Applicable Test									
HS HIROSE ELECTRIC CO., LTD.					SPECIFICATION SHEET			PART NO. DF14H-20P-1.25H(56)	
CODE NO.(OLD) CL		DRAWING NO. ELC4-161459-03			PART NO. CL538-0167-0-56			1/1	